Stackpole Electronics, Inc.

High Power Anti-Sulfur Thin Film Chip Resistor

Resistive Product Solutions

Features:

- Higher power ratings than standard thick film chips
- Absolute TCRs to ±100ppm/°C
- Impervious to Sulfur contamination, no silver present in terminations
- Absolute Tolerances to 1%
- Completely lead free and RoHS compliant without exemptions – does not use lead containing glass
- Comparable in cost to standard thick film chip resistors



Electrical Specifications										
Type / Code	Package Type	Power Rating(2) (Watts) @ 70°C	Maximum Working Voltage(1)	Maximum Overload Voltage	Resistance Temperature	Ohmic Range (Ω) and Tolerance				
					Coefficient	1%, 2%, 5%				
RNCP 0402	0402	0.100W	50V	100V	±100 ppm/°C	1 - 10K				
RNCP 0603	0603	0.125W	150V	300V	±100 ppm/°C	1 - 47K				
RNCP 0805	0805	0.250W	200V	400V	±100 ppm/°C	1 - 100K				
RNCP 1206	1206	0.500W	200V	400V	±100 ppm/°C	1 - 100K				

⁽¹⁾ Lesser of √PR or maximum working voltage.

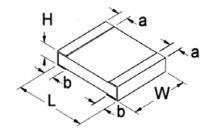
Please refer to the High Power Resistor Application Note (page 4) for more information on designing and implementing high power resistor types.

Performance Characteristics								
Total	Took Oom Williams	Typical						
Test	Test Conditions	1%	2%, 5%					
Short Time Overload	RCWV * 2.5 or Max Overload Voltage, 5 seconds	± 1%	± 2%					
Thermal Shock	MIL-STD-202F Method 107G -55°C to +125°C, 1000 Cycles	± 1%	± 1%					
Load Life	MIL-STD-202F Method 108A RCWV, 125°C, 1.5 Hrs ON, 0.5 Hrs OFF, Total 1000 Hrs	± 2%	± 3%					
Humidity (steady state)	MIL-STD-202F Method 103B 85°C, 85% RH, RCWV 1.5Hrs ON, 0.5Hrs OFF, Total 1000Hrs	± 3%	± 3%					
Resistance to Soldering Heat	MIL-STD-202F Method 210E 260 ± 5°C, 10 ± 1 second	± 1%	± 1%					

^{*} Storage Temperature : 25 ± 3°C; Humidity < 80% RH

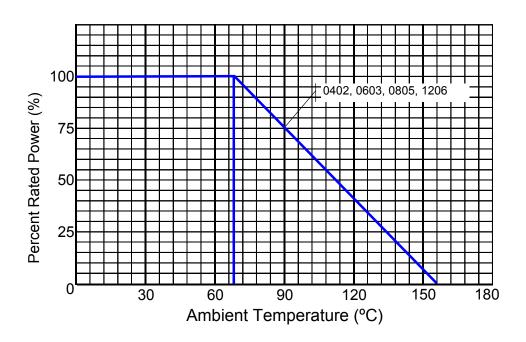
Operating Temperature Range: -55° C to $+70^{\circ}$ C. Above 70° C, the part should be derated linearly to zero power at 155° C.

⁽²⁾ Power rating for each package size is valid if ambient temp ≤80°C and terminal temp ≤105°C.

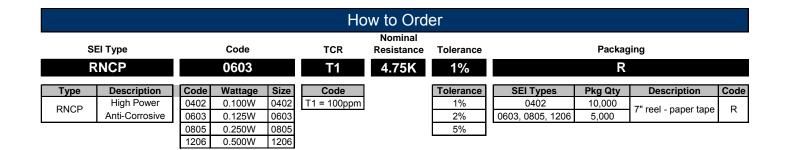


Mechanical Specifications										
Type / Code	L Body Length	W Body Width	H Body Height	a Top Termination	b Bottom Termination	Units				
RNCP 0402	0.040 ± 0.004	0.02 ± 0.002	0.012 ± 0.002	0.01 ± 0.006	0.012 ± 0.006	inches				
	1.00 ± 0.10	0.50 ± 0.05	0.30 ± 0.05	0.25 ± 0.15	0.30 ± 0.15	mm				
RNCP 0603	0.059 ± 0.004	0.032 ± 0.004	0.016 ± 0.004	0.012 ± 0.006	0.016 ± 0.008	inches				
	1.50 ± 0.20	0.80 ± 0.10	0.40 ± 0.10	0.30 ± 0.15	0.40 ± 0.20	mm				
RNCP 0805	0.079 ± 0.006	0.049 ± 0.006	0.020 ± 0.004	0.018 ± 0.008	0.024 ± 0.008	inches				
	2.00 ± 0.15	1.25 ± 0.15	0.50 ± 0.10	0.40 ± 0.20	0.60 ± 0.20	mm				
RNCP 1206	0.122 ± 0.008	0.059 ± 0.008	0.020 ± 0.004	0.020 ± 0.012	0.028 ± 0.008	inches				
	3.10 ± 0.20	1.50 ± 0.20	0.50 ± 0.10	0.50 ± 0.20	0.70 ± 0.20	mm				

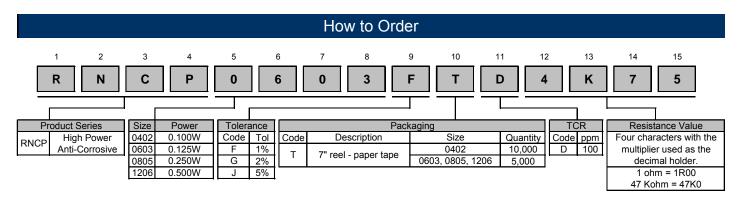
Power Derating Curve:



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New part number format starting January 3rd, 2011:

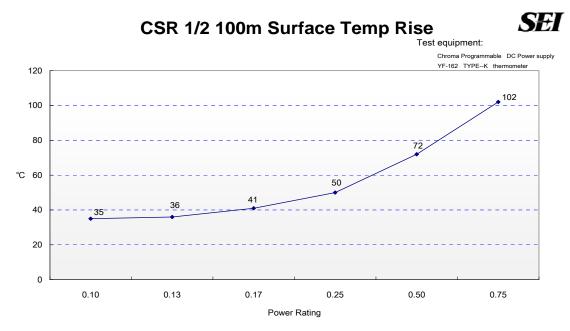


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High Power Chip Resistors and Thermal Management

Stackpole has developed several surface mount resistor series in addition to our current sense resistors, which have had higher power ratings than standard resistor chips. This has caused some uncertainty and even confusion by users as to how to reliably use these resistors at the higher power ratings in their designs.

The data sheets for the RHC, RMCP, RNCP, CSR, CSRN, CSRF, CSS, and CSSH state that the rated power assumes an ambient temperature of no more than 100 degrees C for the CSS / CSSH series and 70 degrees C for all other high power resistor series. In addition, IPC and UL best practices dictate that the combined temperature on any resistor due to power dissipated and ambient air shall be no more than 105C. At first glance this wouldn't seem too difficult, however the graph below shows typical heat rise for the CSR ½ 100 milliohm at full rated power. The heat rise for the RMCP and RNCP would be similar. The RHC with its unique materials, design, and processes would have less heat rise and therefore would be easier to implement for any given customer.



The 102 degrees C heat rise shown here would indicate there will be additional thermal reduction techniques needed to keep this part under 105C total hot spot temperature if this part is to be used at 0.75 watts of power. However, this same part at the usual power rating for this size would have a heat rise of around 72 degrees C. This additional heat rise may be dealt with using wider conductor traces, larger solder pads and land patterns under the solder mask, heavier copper in the conductors, vias through PCB, air movement, and heat sinks, among many other techniques. Because of the variety of methods customers can use to lower the effective heat rise of the circuit, resistor manufacturers simply specify power ratings with the limitations on ambient air temperature and total hot spot temperatures and leave the details of how to best accomplish this to the design engineers. Design guidelines for products in various market segments can vary widely so it would be unnecessarily constraining for a resistor manufacturer to recommend the use of any of these methods over another.

Note: The final resistance value can be affected by the board layout and assembly process, especially the size of the mounting pads and the amount of solder used. This is especially notable for resistance values $\leq 50~\text{m}\Omega$. This should be taken into account when designing.